| L Number | Hits | Search Text | DB | Time stamp |
|-------------|-------|---|--|---------------------|
| 1 | 1 | ("6559537").PN. | USPAT | 2003/09/18 |
| 2 | 13720 | ((heat adj (sink or dissipation or dissipate)) or (thermally adj conductive)) with (case or container or package) | USPAT; US-PGPUB; EPO; JPO; DERWENT; | 2003/09/18 |
| 3 | 6081 | (((heat adj (sink or dissipation or dissipate)) or (thermally adj conductive)) with (case or container or package)) and (chip or die) | IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/09/18 11:08 |
| 4 | 4450 | ((((heat ad) (sink or dissipation or dissipate)) or (thermally ad) conductive)) with (case or container or package)) and (chip or die)) and ((chip or die) with (case or container or package)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/18 11:09 |
| 5 | 3207 | <pre>((((heat adj (sink or dissipation or dissipate)) or (thermally adj conductive)) with (case or container or package)) and (chip or die)) and ((chip or die) with (case or container or package))) and (@ad</pre> | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/18 11:13 |
| 6 | 2469 | <pre>(((((fheat adj (sink or dissipation or dissipate)) or (thermally adj conductive)) with (case or container or package)) and (chip or die)) and ((chip or die) with (case or container or package))) and (@ad<20000905)) and (((heat adj (sink or dissipation or dissipate)) or (thermally adj conductive)) with (chip or die))</pre> | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/18 |
| 7 | 217 | 257/704.ccls. and ((heat adj (sink or dissipation or dissipate)) or (thermally adj conductive)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/09/18 11:12 |
| 8 | 186 | (257/704.ccls. and ((heat adj (sink or dissipation or dissipate)) or (thermally adj conductive))) and (@ad<20000905) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/09/18 11:37 |
| 9 | 2 | (("6191360") or ("6457506")).PN. | USPĀT | 2003/09/18 11:42 |
| 10 | 0 | (("5321222") or ("5521360")).PN. | USPAT | 2003/09/18 |
| | | epxy near rubber | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/18 11:49 |
| 12 | 1967 | epoxy near rubber | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/09/18 |
| 13 | 196 | (cure or curing) with (epoxy and microwave) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2003/09/18 11:53 |
| 14 | 124 | ((cure or curing) with (epoxy and microwave)) and (@ad<19991230) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/09/18 12:27 |

| microwave)) and (@adx19991230)) and (chip or die or (integrated adj circuit)) 16 4 ((((cure or curing) with (epoxy and microwave)) and (@adx19991230)) and (chip or die or (integrated adj circuit))) and bake 17 0 (((cure or curing) with (epoxy and microwave)) and (@adx19991230)) and (bake with (substrate or wafer)) 18 741 ((chip or die) and (bake with (substrate or wafer)) 19 115 ((chip or die) and (bake with (substrate or wafer))) and package 19 115 ((chip or die) and (bake with (substrate or wafer))) and package 20 51 (((chip or die) and (bake with (substrate US-PCFUB) EPO; JPO; DERWENT; IBM TDB USPAT; 2 US-PCFUB) EPO; JPO; DERWENT; IBM TDB USPAT; 2 US-PCFUB; IBM TDB USPAT; 2 US-PCFUB; IBM TDB USPAT; 2 US-PCFUB; IBM TDB USPAT; 12 US-PC | 003/09/18 2:04 003/09/18 2:10 003/09/18 2:11 003/09/18 2:25 |
|--|--|
| 16 | 2:10 003/09/18 2:11 003/09/18 2:25 |
| 16 | 2:10 003/09/18 2:11 003/09/18 2:25 |
| microwave) and (@ad<1999 230) and (chip or die or (integrated adj circuit)) and bake BFO, JPO, DERWENT; IBM TDB USPAT; | 2:10 003/09/18 2:11 003/09/18 2:25 |
| or die or (integrated adj circuit)) and bake bake (((cure or curing) with (epoxy and microwave)) and (8adx19991230)) and (bake with (substrate or wafer)) 18 741 (chip or die) and (bake with (substrate USPAT; or wafer)) 19 115 ((chip or die) and (bake with (substrate USPAT; or wafer))) and package (10 per package) 10 per package (10 per package) 11 c(chip or die) and (bake with (substrate USPAT; or wafer))) and package (10 per package) 12 per package (10 per package) 13 c(chip or die) and (bake with (substrate USPAT; or package) 14 c(chip or die) and (bake with (substrate USPAT; or package) 15 c(chip or die) and (bake with (substrate USPAT; or package) | 003/09/18 2:11 003/09/18 2:25 |
| DERWENT; IEM TDB 17 0 (((cure or curing) with (epoxy and microwave)) and (@ad<19991230)) and (bake US-PGFUB; 1 EPO; JPO; DERWENT; IEM TDB 18 741 (chip or die) and (bake with (substrate or wafer)) 19 115 ((chip or die) and (bake with (substrate or wafer))) and package 19 115 ((chip or die) and (bake with (substrate or wafer))) and package 20 51 (((chip or die) and (bake with (substrate or wafer))) US-PGFUB; 1 EPO; JPO; DERWENT; IEM TDB 19 115 ((chip or die) and (bake with (substrate or wafer))) US-PGFUB; 1 EPO; JPO; DERWENT; IEM TDB 19 115 ((chip or die) and (bake with (substrate or wafer)) US-PGFUB; 1 EPO; JPO; DERWENT; IEM TDB 19 115 ((chip or die) and (bake with (substrate or wafer)) US-PGFUB; 1 EPO; JPO; DERWENT; IEM TDB | 2:11 003/09/18 2:25 003/09/18 |
| 17 0 (((cure or curing) with (epoxy and microwave)) and (@ad<19991230)) and (bake with (substrate or wafer)) USPAT; 2 US-PGFUB; 1 EPO; JPO; DEWENT; 1 EMM_TDB USPAT; 2 US-PGFUB; 1 EPO; JPO; DEWENT; 1 EMM_TDB USPAT; 2 US-PGFUB; 1 EPO; JPO; DEWENT; 1 EPO; JPO; DEWENT; 1 EPO; JPO; DEWENT; 1 EPO; JPO; DEWENT; 1 USPAT; 2 USPAT; 2 USPAT; 2 USPAT; 2 USPAT; 2 USPAT; 2 USPAT; 1 USPAT; 2 USPAT; 1 USPAT; 1 USPAT; 1 USPAT; 1 USPAT; 1 USPAT; 1 USPAT; 2 USPAT; 1 USPA | 2:11 003/09/18 2:25 003/09/18 |
| 17 | 2:11 003/09/18 2:25 003/09/18 |
| microwave)) and (@ad<1999[220]) and (bake US-PGFUB; EPO; JPO; DEWENT; 18 | 2:11 003/09/18 2:25 003/09/18 |
| DEWWENT; IEM TDB 18 741 (chip or die) and (bake with (substrate or wafer)) 19 115 ((chip or die) and (bake with (substrate or wafer)) and package 20 51 (((chip or die) and (bake with (substrate USPAT; 2 US-PGPUB; 1 EPO; JPO; DEWENT) 18 | 2:25 |
| 18 | 2:25 |
| 18 741 (chip or die) and (bake with (substrate USPÄT; 2 or wafer)) USPÄGUS; EPO; JPO; DERWENT; IBM TIB ((chip or die) and (bake with (substrate USPÄT; 2 or wafer)) and package USPÄG; 2 USPÄG; 2 ORWENT; IBM TIB | 2:25 |
| Or wafer)) | 2:25 |
| EPO; JPO; DERWENT; IBM_TDB USPAT; Or wafer)) and package USPAT; Or wafer)) and package USPAT; OR USPAT; OR USPAT; OR WAFER) USPAT; OR US | 003/09/18 |
| DERWENT; ISM TDB ((chip or die) and (bake with (substrate or wafer))) and package or wafer))) and package 20 51 (((chip or die) and (bake with (substrate or wafer))) EPO; JPO; DERWENT; IEM TDB USPĀT; 12 USPĀT; 12 USPĀT; 12 | |
| 19 115 ((chip or die) and (bake with (substrate USPAT; 2 or wafer))) and package USPAT; 2 USPAT; 2 USPAT; 2 USPAT; 2 USPAT; 1 EPO; 1 PO; DERWENT; 1 IBM_TDB USPAT; 1 IBM_TDB USPAT; 1 USPAT; 1 USPAT; 1 USPAT; 1 USPAT; 1 USPAT; 1 USPAT; 2 USPAT; 1 USPAT; 2 U | |
| 19 | |
| or wafer))) and package US-PGFUB; 1 EPO: JPO; DERWENT; IBM TDB 20 51 (((chip or die) and (bake with (substrate USPAT; 2 | 2.11 |
| DERWENT, IBM_TDB (((chip or die) and (bake with (substrate USPAT, 2) | 2:11 |
| 20 51 (((chip or die) and (bake with (substrate USPAT; 2 | |
| 20 51 (((chip or die) and (bake with (substrate USPAT; 2 | |
| | 003/09/18 |
| or wafer))) and package) and US-PGPUB; 1 | 2:12 |
| (@ad<19991230) EPO; JPO; | 2.12 |
| DERWENT; | |
| IBM_TDB | |
| | 003/09/18 |
| | 2:17 |
| (@ad<19991230)) and cure EPO; JPO; DERWENT; | ļ |
| IBM TDB | |
| | 003/09/18 |
| | 2:17 |
| (@ad<19991230)) not ((((chip or die) and EPO; JPO; | |
| (bake with (substrate or wafer))) and DERWENT; | |
| package) and (@ad<19991230)) and cure) IBM_TDB 23 | 003/09/18 |
| | 2:25 |
| EPO; JPO; | |
| DERWENT; | |
| IBM_TDB | |
| | 003/09/18 |
| US-PGPUB; 1 EPO; JPO; | 2:26 |
| DERWENT; | |
| IBM TDB | |
| 25 1 (chip or die) and ((bake and substrate) USPAT; 2 | 003/09/18 |
| | 2:27 |
| EPO; JPO; | (|
| DERWENT; IBM TDB | |
| | 003/09/18 |
| | 2:27 |
| EPO; JPO; | |
| DERWENT, | |
| IBM_TDB | |
| | 003/09/18 |
| (@ad<19991230) US-PGPUB; 1 EPO; JPO; | 2:28 |
| DERWENT; | |
| IBM TDB | |

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